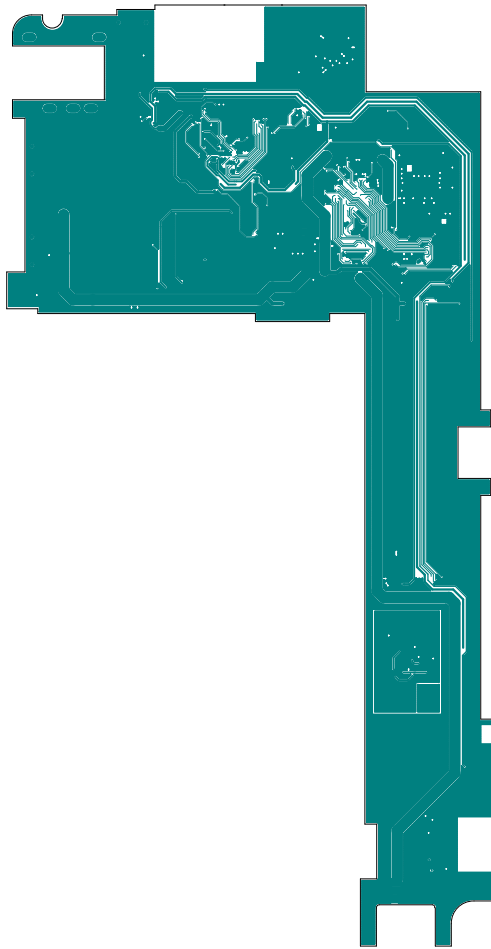


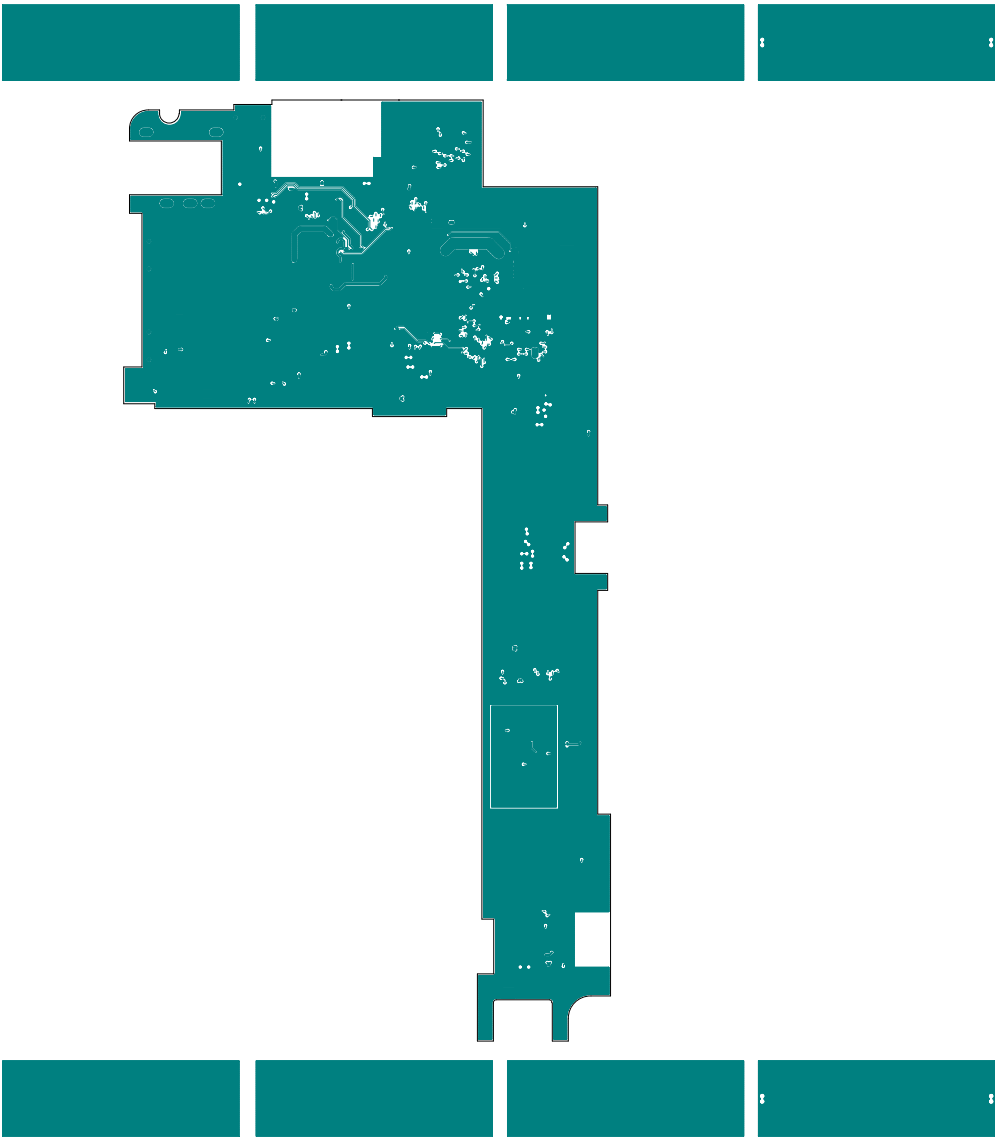

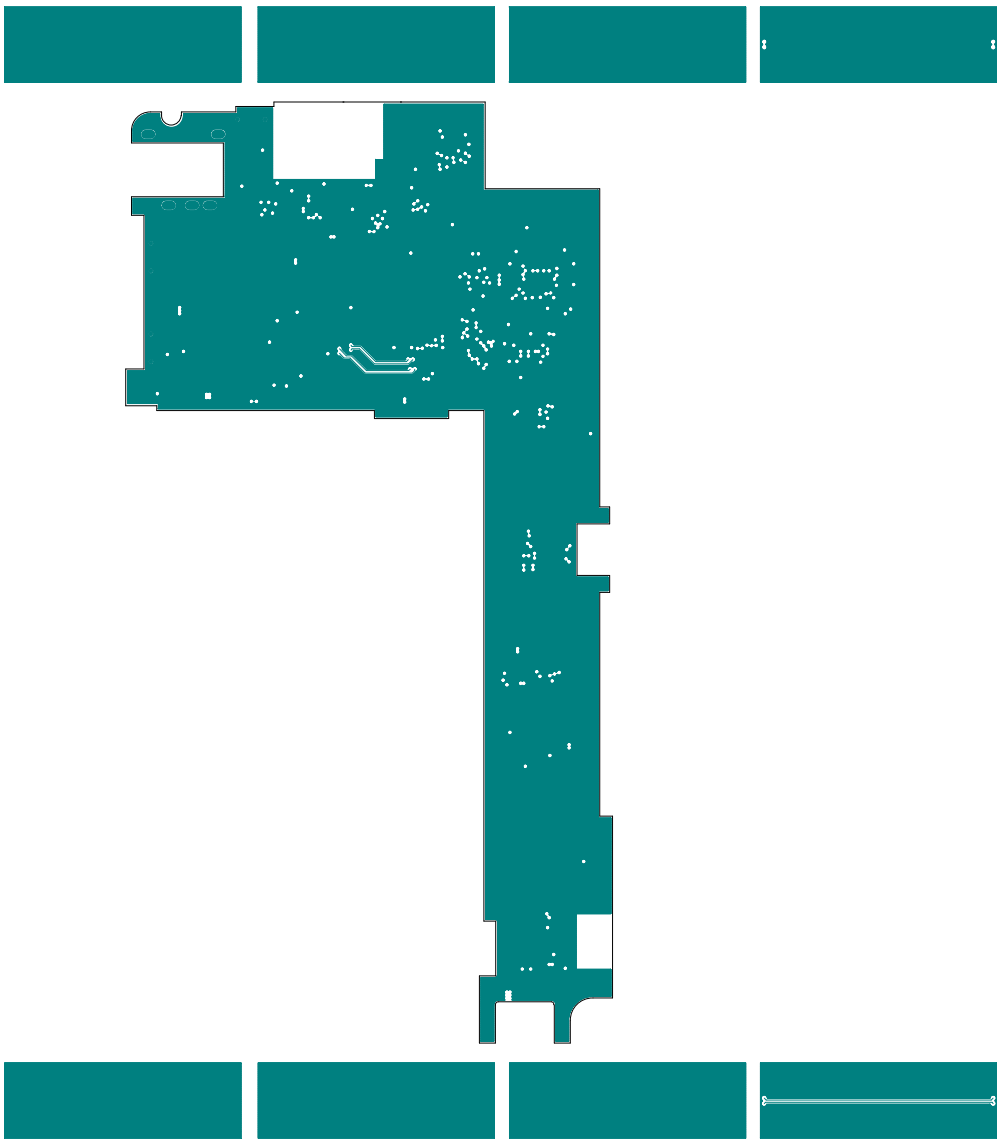
 mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-TOP		
VIA Type	3+4+3	LAYER	1	OF	1
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





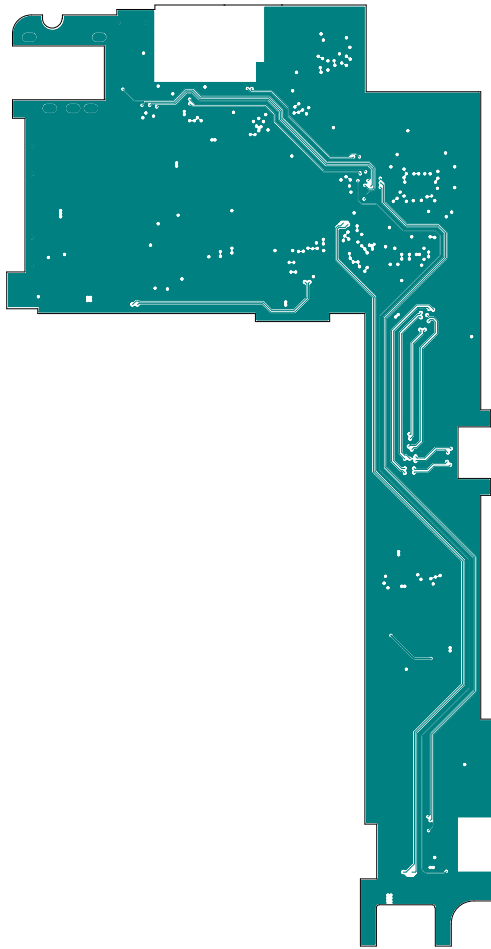
  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-8		
VIA Type	3+4+3	LAYER	1	OF	8
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





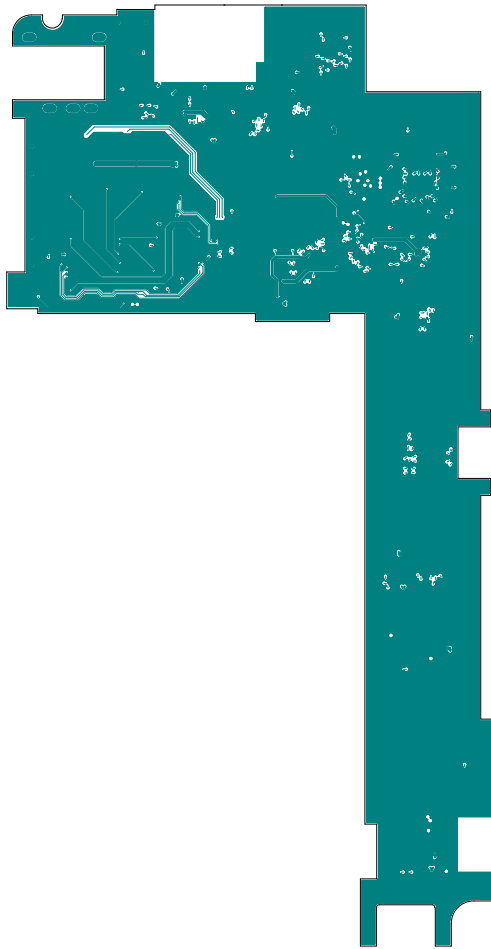
 mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-7		
VIA Type	3+4+3	LAYER	1	OF	7
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-6		
VIA Type	3+4+3	LAYER	1	OF	6
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-5		
VIA Type	3+4+3	LAYER	1	OF	5
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-4		
VIA Type	3+4+3	LAYER	1	OF	4
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





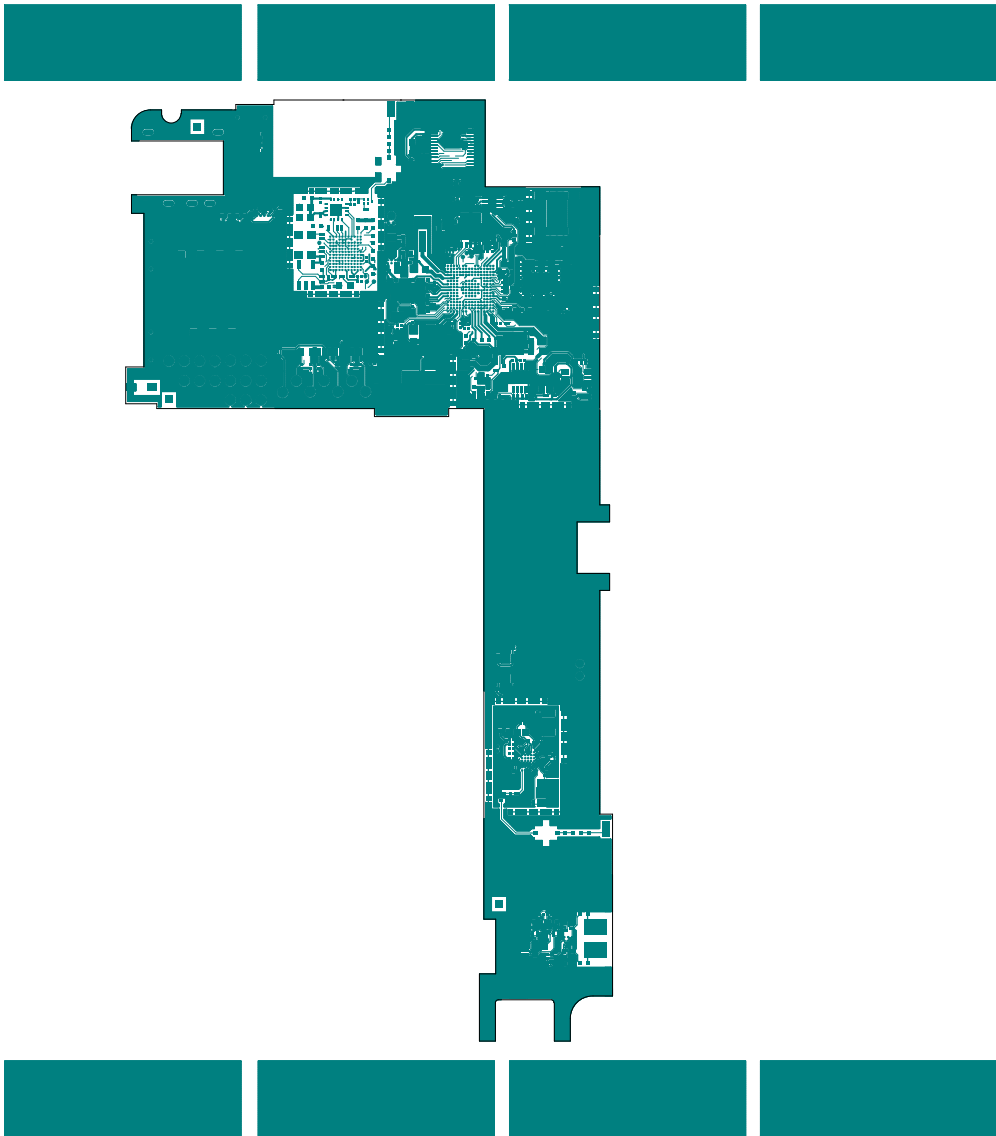
  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-3		
VIA Type	3+4+3	LAYER	1	OF	3
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			





  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-2		
VIA Type	3+4+3	LAYER	1	OF	2
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			



  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-9		
VIA Type	3+4+3	LAYER	1	OF	9
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			



  mobile technology					
BOARD NAME	5002	LAYER NAME	LAYER-Bottom		
VIA Type	3+4+3	LAYER	1	OF	10
H * W	63.9 X 125.13	DATE	2011.01.12		
T =	1.0 MM	REV			